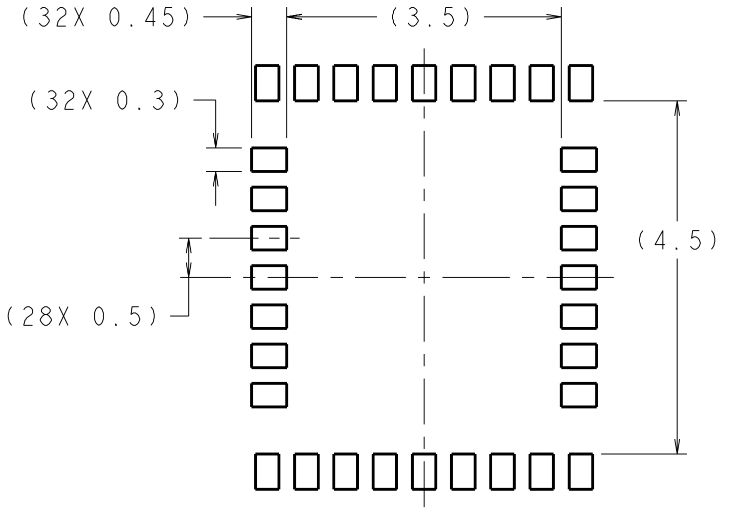
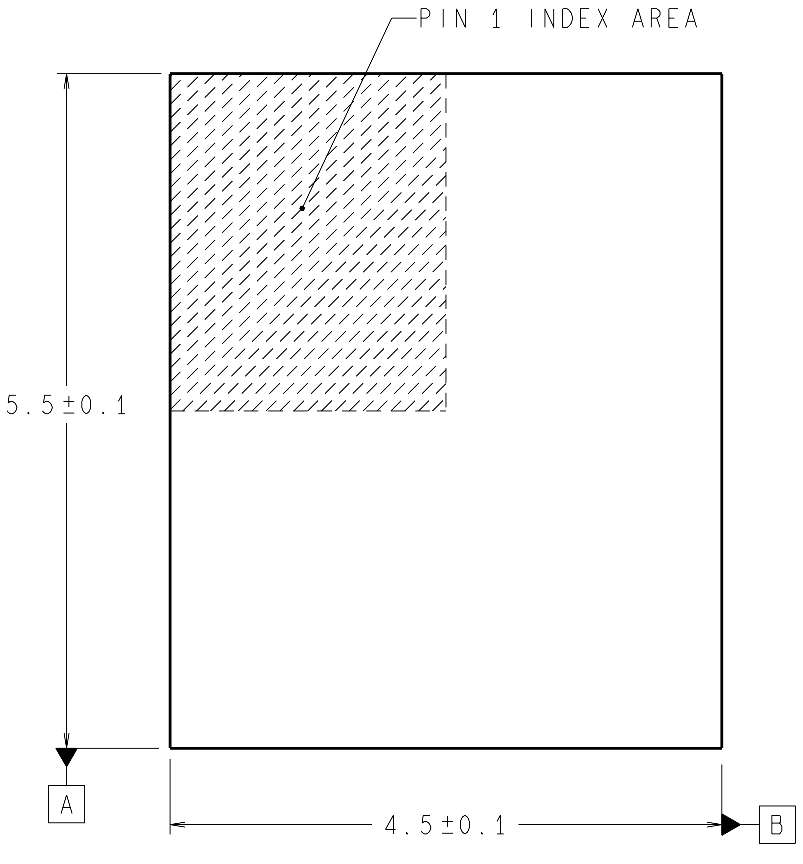
REVISIONS

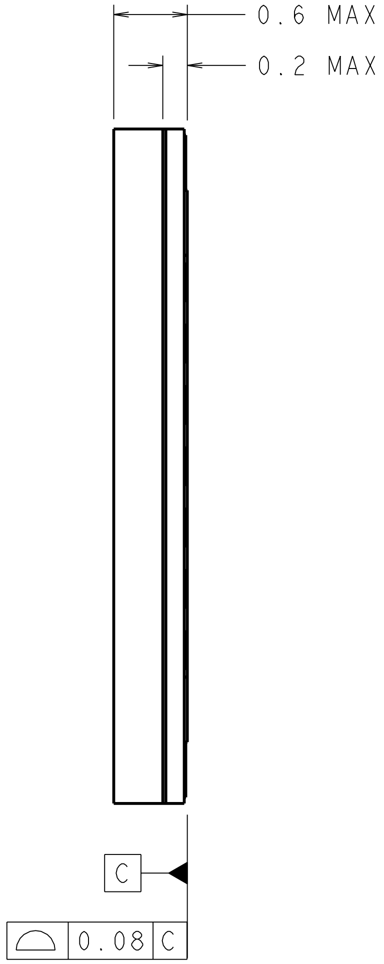
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	356	09/19/2001	TL/AT

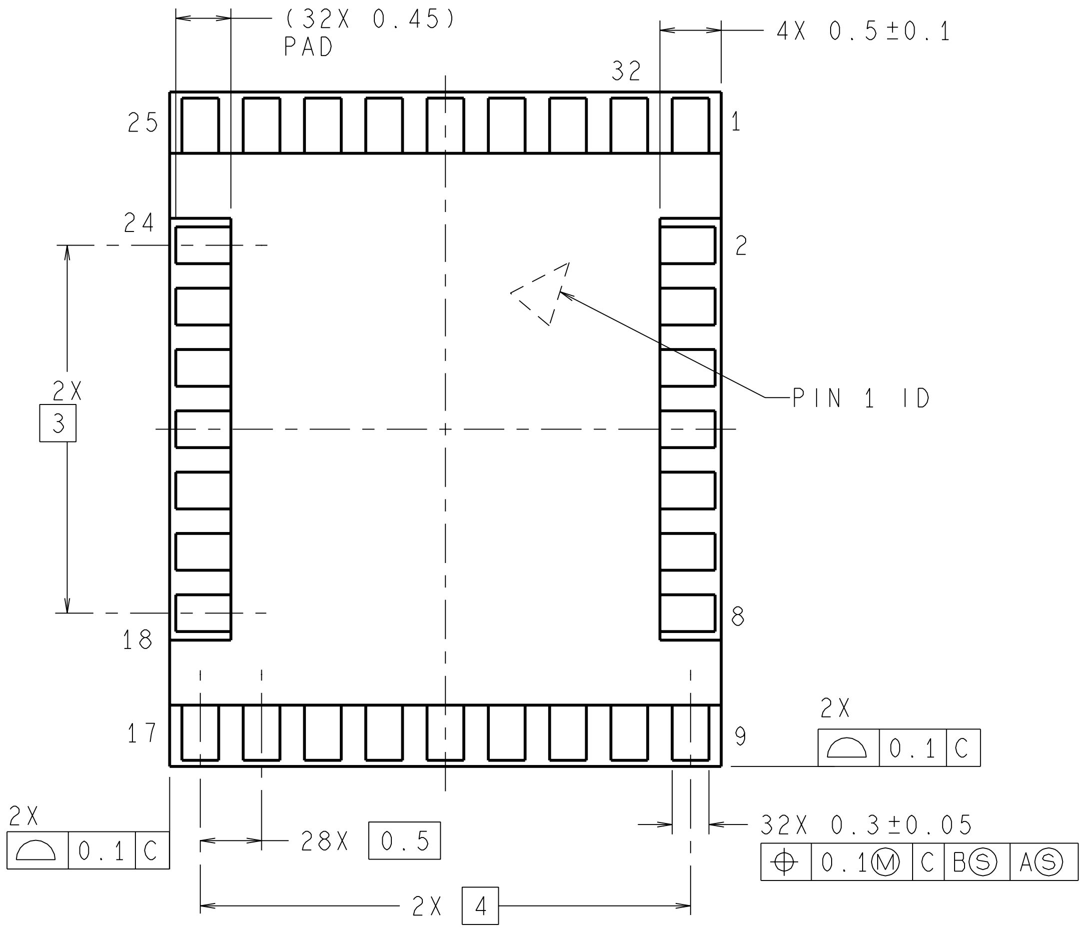


RECOMMENDED LAND PATTERN
1:1 RATIO WITH PACKAGE SOLDER PADS

DIMENSIONS ARE IN MILLIMETERS







NOTES: UNLESS OTHERWISE SPECIFIED.

1. MATERIAL: BT RESIN CCL-HL832-H/S WITH TAIYO PSR4000 AUS5 SOLDER MASK.

2. PLATING: Cu 15 TO 20 MICROMETERS (FULL)
Ni 10 ± 5 MICROMETERS (LEADS ONLY)
Au 0.75 ± 0.25 MICROMETER (LEADS ONLY)

3. REFERENCE JEDEC REGISTRATION MO-208, VARIATION GEEA.

APPROVALS	DATE
DRAWN T. LEQUANG	09/19/2001
DFTG. CHK. MARTA SUCHY	09/19/2001
ENGR. CHK. ANNY TU	09/19/2001

National Semiconductor
2900 Semiconductor Dr, Santa Clara, CA 95052-8090

ULTRA THIN CSP, PLASTIC,
LAMINATED, 4.5 X 5.5 X 0.6 mm
BODY, 32 L, 0.5 mm PITCH

PROJECTION	SCALE	SIZE	DRAWING NUMBER	REV
INCH [MM]	N/A	C	(SC)MKT-SLE32A	A

FORMERLY: N/A
SHEET 1 of 1